

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2066isc6#trmpbf

(Engineering Calculation)

SC70 (COL)

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**TOTAL MASS (g) : 0.009877**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000738	1000000	74718.140625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.003032	975000	306972.09375		
		Iron (Fe)	7439-89-6	0.000075	24000	7593.30761719		
		Phosphorus (P)	7723-14-0	0.000001	300	101.244094849		
		Zinc (Zn)	7440-66-6	0.000002	700	202.488189697		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003110</b>	<b>1000000</b>	<b>314869.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003408	1000000	345052		
		<b>External Plating Total:</b>				<b>0.003408</b>	<b>1000000</b>	<b>345052</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000004	50000	404.976379395		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000024	300000	2429.85839844		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000053	650000	5365.93701172		
<b>Die Attach Total:</b>				<b>0.000081</b>	<b>1000000</b>	<b>8200.77148438</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000147	58000	14882.8818359		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.002261	890000	228912.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000127	50000	12858.0009766		
		Carbon Black (C)	1333-86-4	0.000005	2000	506.220428467		
		<b>Encapsulation Total:</b>				<b>0.002540</b>	<b>1000000</b>	<b>257160.015625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000000	0	0		
					<b>TOTAL MASS (g) :</b>	<b>0.009877</b>		